

Welcome to **E-XFL.COM** 

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, LVD, POR, PWM, WDT
Number of I/O	51
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	•
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f65j90-i-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

TABLE 1-4: PIC18F8XJ90 PINOUT I/O DESCRIPTIONS

Din Nama	Pin Number	Pin	Buffer	Description
Pin Name	TQFP	Type	Type	Description
MCLR	9	I	ST	Master Clear (input) or programming voltage (input). This pin is an active-low Reset to the device.
OSC1/CLKI/RA7 OSC1 CLKI	49	1	CMOS CMOS	Oscillator crystal or external clock input. Oscillator crystal input. External clock source input. Always associated with pin function OSC1. (See related OSC1/CLKI, OSC2/CLKO pins.)
RA7		I/O	TTL	General purpose I/O pin.
OSC2/CLKO/RA6 OSC2	50	0	_	Oscillator crystal or clock output. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode.
CLKO		0	_	In EC modes, OSC2 pin outputs CLKO, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
RA6		I/O	TTL	General purpose I/O pin.
				PORTA is a bidirectional I/O port.
RA0/AN0 RA0 AN0	30	I/O I	TTL Analog	Digital I/O. Analog Input 0.
RA1/AN1/SEG18 RA1 AN1 SEG18	29	I/O I O	TTL Analog Analog	Digital I/O. Analog Input 1. SEG18 output for LCD.
RA2/AN2/VREF- RA2 AN2 VREF-	28	I/O I I	TTL Analog Analog	Digital I/O. Analog Input 2. A/D reference voltage (low) input.
RA3/AN3/VREF+ RA3 AN3 VREF+	27	I/O I I	TTL Analog Analog	Digital I/O. Analog Input 3. A/D reference voltage (high) input.
RA4/T0CKI/SEG14 RA4 T0CKI SEG14	34	I/O I O	ST/OD ST Analog	Digital I/O. Open-drain when configured as output. Timer0 external clock input. SEG14 output for LCD.
RA5/AN4/SEG15 RA5 AN4 SEG15	33	I/O I O	TTL Analog Analog	Digital I/O. Analog Input 4. SEG15 output for LCD.
RA6				See the OSC2/CLKO/RA6 pin.
RA7				See the OSC1/CLKI/RA7 pin.

**Legend:** TTL = TTL compatible input CMOS = CMOS compatible input or output

ST = Schmitt Trigger input with CMOS levels Analog = Analog input O = Output

P = Power OD = Open-Drain (no P diode to VDD)

 $I^2C^{TM} = I^2C/SMBus$ 

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

TABLE 1-4: PIC18F8XJ90 PINOUT I/O DESCRIPTIONS (CONTINUED)

Din Name	Pin Number	Pin	Buffer	Description
Pin Name	TQFP	Type	Type	Description
				PORTJ is a bidirectional I/O port.
RJ0	62	I/O	ST	Digital I/O.
RJ1/SEG33 RJ1 SEG33	61	I/O O	ST Analog	Digital I/O. SEG33 output for LCD.
RJ2/SEG34 RJ2 SEG34	60	I/O O	ST Analog	Digital I/O. SEG34 output for LCD.
RJ3/SEG35 RJ3 SEG35	59	I/O O	ST Analog	Digital I/O. SEG35 output for LCD.
RJ4/SEG39 RJ4 SEG39	39	I/O O	ST Analog	Digital I/O. SEG39 output for LCD.
RJ5/SEG38 RJ5 SEG38	40	I/O O	ST Analog	Digital I/O SEG38 output for LCD.
RJ6/SEG37 RJ6 SEG37	41	I/O O	ST Analog	Digital I/O. SEG37 output for LCD.
RJ7/SEG36 RJ7 SEG36	42	I/O O	ST Analog	Digital I/O. SEG36 output for LCD.
Vss	11, 31, 51, 70	Р	_	Ground reference for logic and I/O pins.
VDD	32, 48, 71	Р	_	Positive supply for logic and I/O pins.
AVss	26	Р	_	Ground reference for analog modules.
AVDD	25	Р	_	Positive supply for analog modules.
ENVREG	24	ı	ST	Enable for on-chip voltage regulator.
VDDCORE/VCAP VDDCORE	12	Р	_	Core logic power or external filter capacitor connection.  Positive supply for microcontroller core logic (regulator disabled).
VCAP		Р	_	External filter capacitor connection (regulator enabled).

Legend: TTL = TTL compatible input

CMOS = CMOS compatible input or output

ST = Schmitt Trigger input with CMOS levels

Analog = Analog input

I = Input

O = Output OD = Open-Drain (no P diode to VDD)

P = Power

 $I^2C^{TM} = I^2C/SMBus$ 

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

### 2.0 GUIDELINES FOR GETTING STARTED WITH PIC18FJ MICROCONTROLLERS

### 2.1 Basic Connection Requirements

Getting started with the PIC18F85J90 family family of 8-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

- All VDD and Vss pins (see Section 2.2 "Power Supply Pins")
- All AVDD and AVSs pins, regardless of whether or not the analog device features are used (see Section 2.2 "Power Supply Pins")
- MCLR pin (see Section 2.3 "Master Clear (MCLR) Pin")
- ENVREG (if implemented) and VCAP/VDDCORE pins (see Section 2.4 "Voltage Regulator Pins (ENVREG and VCAP/VDDCORE)")

These pins must also be connected if they are being used in the end application:

- PGC/PGD pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see Section 2.5 "ICSP Pins")
- OSCI and OSCO pins when an external oscillator source is used

(see Section 2.6 "External Oscillator Pins")

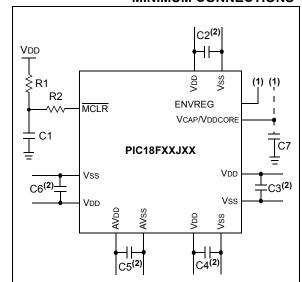
Additionally, the following pins may be required:

 VREF+/VREF- pins are used when external voltage reference for analog modules is implemented

**Note:** The AVDD and AVSS pins must always be connected, regardless of whether any of the analog modules are being used.

The minimum mandatory connections are shown in Figure 2-1.

## FIGURE 2-1: RECOMMENDED MINIMUM CONNECTIONS



### Key (all values are recommendations):

C1 through C6: 0.1  $\mu$ F, 20V ceramic

C7: 10  $\mu\text{F}$ , 6.3V or greater, tantalum or ceramic

R1:  $10 \text{ k}\Omega$ R2:  $100\Omega$  to  $470\Omega$ 

Note 1: See Section 2.4 "Voltage Regulator Pins (ENVREG and VCAP/VDDCORE)" for explanation of ENVREG pin connections.

2: The example shown is for a PIC18F device with five VDD/Vss and AVDD/AVss pairs. Other devices may have more or less pairs; adjust the number of decoupling capacitors appropriately.

## 2.4 Voltage Regulator Pins (ENVREG and VCAP/VDDCORE)

The on-chip voltage regulator enable pin, ENVREG, must always be connected directly to either a supply voltage or to ground. Tying ENVREG to VDD enables the regulator, while tying it to ground disables the regulator. Refer to **Section 23.3 "On-Chip Voltage Regulator"** for details on connecting and using the on-chip regulator.

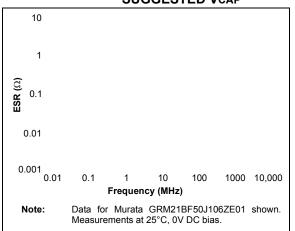
When the regulator is enabled, a low-ESR (<  $5\Omega$ ) capacitor is required on the VCAP/VDDCORE pin to stabilize the voltage regulator output voltage. The VCAP/VDDCORE pin must not be connected to VDD and must use a capacitor of 10  $\mu F$  connected to ground. The type can be ceramic or tantalum. A suitable example is the Murata GRM21BF50J106ZE01 (10  $\mu F,~6.3V$ ) or equivalent. Designers may use Figure 2-3 to evaluate ESR equivalence of candidate devices.

It is recommended that the trace length not exceed 0.25 inch (6 mm). Refer to **Section 26.0 "Electrical Characteristics"** for additional information.

When the regulator is disabled, the VCAP/VDDCORE pin must be tied to a voltage supply at the VDDCORE level. Refer to **Section 26.0** "**Electrical Characteristics**" for information on VDD and VDDCORE.

Note that the "LF" versions of some low pin count PIC18FJ parts (e.g., the PIC18LF45J10) do not have the ENVREG pin. These devices are provided with the voltage regulator permanently disabled; they must always be provided with a supply voltage on the VDDCORE pin.

FIGURE 2-3: FREQUENCY vs. ESR
PERFORMANCE FOR
SUGGESTED VCAP



#### 2.5 ICSP Pins

The PGC and PGD pins are used for In-Circuit Serial Programming  $^{\text{TM}}$  (ICSP $^{\text{TM}}$ ) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed  $100\Omega$ .

Pull-up resistors, series diodes, and capacitors on the PGC and PGD pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pin input voltage high (VIH) and input low (VIL) requirements.

For device emulation, ensure that the "Communication Channel Select" (i.e., PGCx/PGDx pins) programmed into the device matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to Section 24.0 "Development Support".

### 3.2 Control Registers

The OSCCON register (Register 3-1) controls the main aspects of the device clock's operation. It selects the oscillator type to be used, which of the power-managed modes to invoke and the output frequency of the INTOSC source. It also provides status on the oscillators.

The OSCTUNE register (Register 3-2) controls the tuning and operation of the internal oscillator block. It also implements the PLLEN bits, which control the operation of the Phase Locked Loop (PLL) in Internal Oscillator modes (see **Section 3.4.3 "PLL Frequency Multiplier"**).

### REGISTER 3-1: OSCCON: OSCILLATOR CONTROL REGISTER

R/W-0	R/W-1	R/W-0	R/W-0	R <sup>(1)</sup>	R-0	R/W-0	R/W-0
IDLEN	IRCF2 <sup>(2)</sup>	IRCF1 <sup>(2)</sup>	IRCF0 <sup>(2)</sup>	OSTS	IOFS	SCS1 <sup>(4)</sup>	SCS0 <sup>(4)</sup>
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, rea	ad as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 IDLEN: Idle Enable bit

1 = Device enters an Idle mode when a SLEEP instruction is executed

0 = Device enters Sleep mode when a SLEEP instruction is executed

bit 6-4 IRCF<2:0>: INTOSC Source Frequency Select bits<sup>(2)</sup>

111 = 8 MHz (INTOSC drives clock directly)

110 = 4 MHz

101 = 2 MHz

100 = 1 MHz (default)

011 = 500 kHz

010 = 250 kHz

001 = 125 kHz

000 = 31 kHz (from either INTOSC/256 or INTRC)(3)

bit 3 OSTS: Oscillator Start-up Time-out Status bit (1)

1 = Oscillator Start-up Timer (OST) time-out has expired; primary oscillator is running

0 = Oscillator Start-up Timer (OST) time-out is running; primary oscillator is not ready

bit 2 IOFS: INTOSC Frequency Stable bit

1 = Fast RC oscillator frequency is stable

0 = Fast RC oscillator frequency is not stable

bit 1-0 SCS<1:0:> System Clock Select bits<sup>(4)</sup>

11 = Internal oscillator block

10 = Primary oscillator

01 = Timer1 oscillator

When FOSC2 = 1:

00 = Primary oscillator

When FOSC2 = 0:

00 = Internal oscillator

- Note 1: Reset state depends on state of the IESO Configuration bit.
  - 2: Modifying these bits will cause an immediate clock frequency switch if the internal oscillator is providing the device clocks.
  - 3: Source selected by the INTSRC bit (OSCTUNE<7>), see text.
  - 4: Modifying these bits will cause an immediate clock source switch.

TABLE 5-2: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices		Power-on Reset, Brown-out Reset	MCLR Resets WDT Reset RESET Instruction Stack Resets CM Resets	Wake-up via WDT or Interrupt
CCPR2L	PIC18F6XJ90	PIC18F8XJ90	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP2CON	PIC18F6XJ90	PIC18F8XJ90	00 0000	00 0000	uu uuuu
SPBRG2	PIC18F6XJ90	PIC18F8XJ90	0000 0000	0000 0000	uuuu uuuu
RCREG2	PIC18F6XJ90	PIC18F8XJ90	0000 0000	0000 0000	uuuu uuuu
TXREG2	PIC18F6XJ90	PIC18F8XJ90	0000 0000	0000 0000	uuuu uuuu
TXSTA2	PIC18F6XJ90	PIC18F8XJ90	0000 -010	0000 -010	uuuu -uuu
RCSTA2	PIC18F6XJ90	PIC18F8XJ90	0000 000x	0000 000x	uuuu uuuu

- **Legend:** u = unchanged, x = unknown, = unimplemented bit, read as '0', <math>q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.
- Note 1: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.
  - 2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).
  - **3:** One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).
  - 4: See Table 5-1 for Reset value for specific condition.
  - **5:** Bits 6 and 7 of PORTA, LATA and TRISA are enabled depending on the oscillator mode selected. When not enabled as PORTA pins, they are disabled and read as '0'.

### 6.0 MEMORY ORGANIZATION

There are two types of memory in PIC18 Flash microcontroller devices:

- · Program Memory
- · Data RAM

As Harvard architecture devices, the data and program memories use separate busses; this allows for concurrent access of the two memory spaces.

Additional detailed information on the operation of the Flash program memory is provided in **Section 7.0 "Flash Program Memory"**.

### 6.1 Program Memory Organization

PIC18 microcontrollers implement a 21-bit program counter which is capable of addressing a 2-Mbyte program memory space. Accessing a location between the upper boundary of the physically implemented memory and the 2-Mbyte address will return all '0's (a NOP instruction).

The entire PIC18F85J90 family offers a range of on-chip Flash program memory sizes, from 8 Kbytes (up to 4,096 single-word instructions) to 32 Kbytes (32,768 single-word instructions). The program memory maps for individual family members are shown in Figure 6-1.

FIGURE 6-1: MEMORY MAPS FOR PIC18F85J90 FAMILY DEVICES

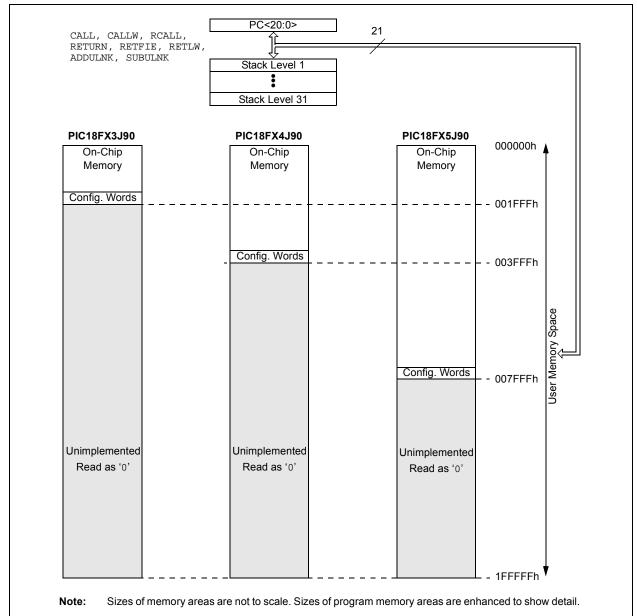


TABLE 10-7: PORTC FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RC0/T1OSO/	RC0	0	0	DIG	LATC<0> data output.
T13CKI		1		ST	PORTC<0> data input.
	T10S0	х	0	ANA	Timer1 oscillator output; enabled when Timer1 oscillator is enabled. Disables digital I/O and LCD segment driver.
	T13CKI	1	I	ST	Timer1/Timer3 counter input.
RC1/T1OSI/	RC1	0	0	DIG	LATC<1> data output.
CCP2/SEG32		1	ı	ST	PORTC<1> data input.
	T1OSI	х	I	ANA	Timer1 oscillator input.
	CCP2 <sup>(1)</sup>	0	0	DIG	CCP2 compare/PWM output.
		1	I	ST	CCP2 capture input.
	SEG32	х	0	ANA	LCD Segment 32 output; disables all other pin functions.
RC2/CCP1/ SEG13	RC2	0	0	DIG	LATC<2> data output.
02010	0004	1	1	ST	PORTC<2> data input.
	CCP1	0	0	DIG	CCP1 compare/PWM output; takes priority over port data.
	SEG13	1	0	ST	CCP1 capture input.  LCD Segment 13 output; disables all other pin functions.
RC3/SCK/SCL/	RC3	x	0	ANA	LATC<3> data output.
SEG17	RCS	0	<u> </u>	ST	PORTC<3> data output.
	SCK	0	0	DIG	SPI clock output (MSSP module); takes priority over port data.
	OOK	1		ST	SPI clock input (MSSP module).
	SCL	0	0	DIG	I <sup>2</sup> C™ clock output (MSSP module); takes priority over port data.
	002	1	ı	I2C	I <sup>2</sup> C clock input (MSSP module); input type depends on module setting.
	SEG17	х	0	ANA	LCD Segment 17 output; disables all other pin functions.
RC4/SDI/SDA/	RC4	0	0	DIG	LATC<4> data output.
SEG16		1	I	ST	PORTC<4> data input.
	SDI		I	ST	SPI data input (MSSP module).
	SDA	1	0	DIG	I <sup>2</sup> C data output (MSSP module); takes priority over port data.
		1	1	I2C	I <sup>2</sup> C data input (MSSP module); input type depends on module setting.
	SEG16	х	0	ANA	LCD Segment 16 output; disables all other pin functions.
RC5/SDO/	RC5	0	0	DIG	LATC<5> data output.
SEG12		1	I	ST	PORTC<5> data input.
	SDO	0	0	DIG	SPI data output (MSSP module).
	SEG12	х	0	ANA	LCD Segment 12 output; disables all other pin functions.
RC6/TX1/CK1/ SEG27	RC6	0	0	DIG	LATC<6> data output.
SEG21		1	ı	ST	PORTC<6> data input.
	TX1	1	0	DIG	Synchronous serial data output (EUSART module); takes priority over port data.
	CK1	1	0	DIG	Synchronous serial data input (EUSART module); user must configure as an input.
	05007	1	1	ST	Synchronous serial clock input (EUSART module).
DOZIDYA IDTA	SEG27	x	0	ANA	LCD Segment 27 output; disables all other pin functions.
RC7/RX1/DT1/ SEG28	RC7	0	0	DIG	LATC<7> data output.
	DV4	1	- 1	ST	PORTC<7> data input.
	RX1	1	-	ST	Asynchronous serial receive data input (EUSART module).
	DT1	1	0	DIG	Synchronous serial data output (EUSART module); takes priority over port data.
	SEGOO	1	-	ST	Synchronous serial data input (EUSART module); user must configure as an input.
	SEG28	Х	0	ANA	LCD Segment 28 output; disables all other pin functions.

**Legend:** O = Output, I = Input, ANA = Analog Signal, DIG = Digital Output, ST = Schmitt Trigger Buffer Input, TTL = TTL Buffer Input,  $ICC = I^2C/SMBus$  Buffer Inp

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

### 15.4.2 PWM DUTY CYCLE

The PWM duty cycle is specified by writing to the CCPR2L register and to the CCP2CON<5:4> bits. Up to 10-bit resolution is available. The CCPR2L contains the eight MSbs and the CCP2CON<5:4> contains the two LSbs. This 10-bit value is represented by CCPR2L:CCP2CON<5:4>. The following equation is used to calculate the PWM duty cycle in time:

### **EQUATION 15-2:**

CCPR2L and CCP2CON<5:4> can be written to at any time, but the duty cycle value is not latched into CCPR2H until after a match between PR2 and TMR2 occurs (i.e., the period is complete). In PWM mode, CCPR2H is a read-only register.

The CCPR2H register and a 2-bit internal latch are used to double-buffer the PWM duty cycle. This double-buffering is essential for glitchless PWM operation.

When the CCPR2H and 2-bit latch match TMR2, concatenated with an internal 2-bit Q clock or 2 bits of the TMR2 prescaler, the CCP2 pin is cleared.

The maximum PWM resolution (bits) for a given PWM frequency is given by the equation:

### **EQUATION 15-3:**

PWM Resolution (max) = 
$$\frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log(2)}$$
 bits

**Note:** If the PWM duty cycle value is longer than the PWM period, the CCP2 pin will not be cleared.

TABLE 15-4: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 40 MHz

PWM Frequency	2.44 kHz	9.77 kHz	39.06 kHz	156.25 kHz	312.50 kHz	416.67 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	FFh	FFh	FFh	3Fh	1Fh	17h
Maximum Resolution (bits)	14	12	10	8	7	6.58

## 16.3.3.3 M2 (Resistor Ladder with Software Contrast)

M2 operation also uses the LCD regulator but disables the charge pump. The regulator's internal voltage reference remains active as a way to regulate contrast. It is used in cases where the current requirements of the LCD exceed the capacity of the regulator's charge pump.

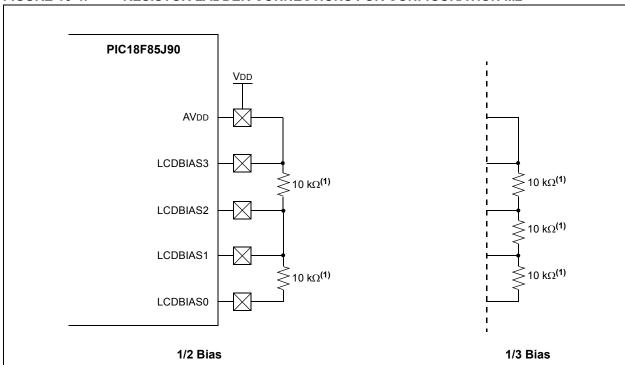
In this configuration, the LCD bias voltage levels are created by an external resistor voltage divider connected across LCDBIAS0 through LCDBIAS3, with the top of the divider tied to VDD (Figure 16-4). The potential at the bottom of the ladder is determined by the LCD regulator's voltage reference, tied internally to LCDBIAS0. The bias type is determined by the voltages on the LCDBIAS pins, which are controlled by the

configuration of the resistor ladder. Most applications using M2 will use a 1/3 or 1/2 Bias type. While Static Bias can also be used, it offers extremely limited contrast range and additional current consumption over other bias generation modes.

Like M1, the LCDBIAS bits can be used to control contrast, limited by the level of VDD supplied to the device. Also, since there is no capacitor required across VLCAP1 and VLCAP2, these pins are available as digital I/O ports, RG2 and RG3.

M2 is selected by clearing the CKSEL<1:0> bits and setting the CPEN bit.

FIGURE 16-4: RESISTOR LADDER CONNECTIONS FOR CONFIGURATION M2



Bias Level at Pin	Bias Type				
	1/2 Bias	1/3 Bias			
LCDBIAS0	(Internal low reference voltage)	(Internal low reference voltage)			
LCDBIAS1	1/2 VBIAS	1/3 VBIAS			
LCDBIAS2	1/2 VBIAS	2/3 VBIAS			
LCDBIAS3	VBIAS (up to AVDD)	VBIAS (up to AVDD)			

**Note 1:** These values are provided for design guidance only; they should be optimized for the application by the designer based on the actual LCD specifications.

FIGURE 17-5: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

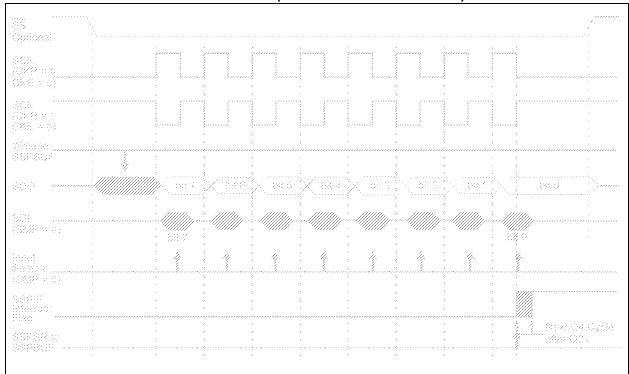
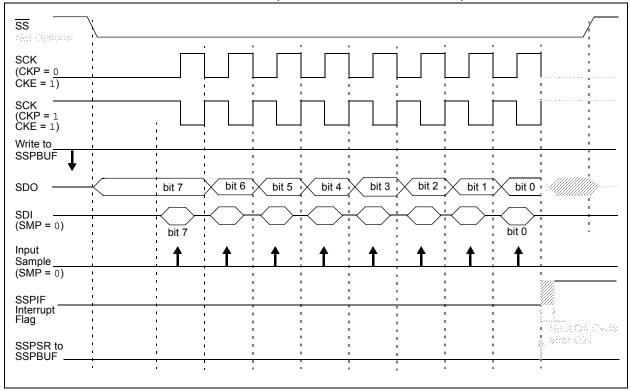


FIGURE 17-6: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



#### 17.4.2 OPERATION

The MSSP module functions are enabled by setting the MSSP Enable bit, SSPEN (SSPCON1<5>).

The SSPCON1 register allows control of the I<sup>2</sup>C operation. Four mode selection bits (SSPCON1<3:0>) allow one of the following I<sup>2</sup>C modes to be selected:

- I<sup>2</sup>C Master mode, clock = (Fosc/4) x (SSPADD + 1)
- I<sup>2</sup>C Slave mode (7-bit address)
- I<sup>2</sup>C Slave mode (10-bit address)
- I<sup>2</sup>C Slave mode (7-bit address) with Start and Stop bit interrupts enabled
- I<sup>2</sup>C Slave mode (10-bit address) with Start and Stop bit interrupts enabled
- I<sup>2</sup>C Firmware Controlled Master mode, slave is Idle

Selection of any I<sup>2</sup>C mode, with the SSPEN bit set, forces the SCL and SDA pins to be open-drain, provided these pins are programmed to inputs by setting the appropriate TRISC or TRISD bits. To ensure proper operation of the module, pull-up resistors must be provided externally to the SCL and SDA pins.

#### 17.4.3 SLAVE MODE

In Slave mode, the SCL and SDA pins must be configured as inputs (TRISC<4:3> set). The MSSP module will override the input state with the output data when required (slave-transmitter).

The I<sup>2</sup>C Slave mode hardware will always generate an interrupt on an exact address match. In addition, address masking will also allow the hardware to generate an interrupt for more than one address (up to 31 in 7-bit addressing and up to 63 in 10-bit addressing). Through the mode select bits, the user can also choose to interrupt on Start and Stop bits.

When an address is matched, or the data transfer after an address match is received, the hardware automatically will generate the Acknowledge (ACK) pulse and load the SSPBUF register with the received value currently in the SSPSR register.

Any combination of the following conditions will cause the MSSP module not to give this  $\overline{\mathsf{ACK}}$  pulse:

- The Buffer Full bit, BF (SSPSTAT<0>), was set before the transfer was received.
- The overflow bit, SSPOV (SSPCON1<6>), was set before the transfer was received.

In this case, the SSPSR register value is not loaded into the SSPBUF, but bit SSPIF is set. The BF bit is cleared by reading the SSPBUF register, while bit SSPOV is cleared through software.

The SCL clock input must have a minimum high and low for proper operation. The high and low times of the I<sup>2</sup>C specification, as well as the requirement of the MSSP module, are shown in timing parameter 100 and parameter 101.

#### 17.4.3.1 Addressing

Once the MSSP module has been enabled, it waits for a Start condition to occur. Following the Start condition, the 8 bits are shifted into the SSPSR register. All incoming bits are sampled with the rising edge of the clock (SCL) line. The value of register SSPSR<7:1> is compared to the value of the SSPADD register. The address is compared on the falling edge of the eighth clock (SCL) pulse. If the addresses match and the BF and SSPOV bits are clear, the following events occur:

- The SSPSR register value is loaded into the SSPBUF register.
- 2. The Buffer Full bit, BF, is set.
- 3. An ACK pulse is generated.
- The MSSP Interrupt Flag bit, SSPIF, is set (and interrupt is generated, if enabled) on the falling edge of the ninth SCL pulse.

In 10-Bit Address mode, two address bytes need to be received by the slave. The five Most Significant bits (MSbs) of the first address byte specify if this is a 10-bit address. Bit, R/W (SSPSTAT<2>), must specify a write so the slave device will receive the second address byte. For a 10-bit address, the first byte would equal '11110 A9 A8 0', where 'A9' and 'A8' are the two MSbs of the address. The sequence of events for 10-bit address is as follows, with steps 7 through 9 for the slave-transmitter:

- 1. Receive the first (high) byte of address (bits, SSPIF, BF and UA (SSPSTAT<1>), are set).
- 2. Update the SSPADD register with the second (low) byte of address (clears bit, UA, and releases the SCL line).
- 3. Read the SSPBUF register (clears bit, BF) and clear flag bit, SSPIF.
- Receive second (low) byte of address (SSPIF, BF and UA bits are set).
- Update the SSPADD register with the first (high) byte of address. If match releases SCL line, this will clear the UA bit.
- 6. Read the SSPBUF register (clears bit, BF) and clear flag bit, SSPIF.
- 7. Receive Repeated Start condition.
- 8. Receive first (high) byte of address (SSPIF and BF bits are set).
- 9. Read the SSPBUF register (clears BF bit) and clear flag bit, SSPIF.

### REGISTER 23-1: CONFIG1L: CONFIGURATION REGISTER 1 LOW (BYTE ADDRESS 300000h)

R/WO-1	R/WO-1	R/WO-1	U-0	U-0	U-0	U-0	R/WO-1
DEBUG	XINST	STVREN	_	_	_	_	WDTEN
bit 7							bit 0

Legend:

R = Readable bit WO = Write-Once bit U = Unimplemented bit, read as '0'

-n = Value when device is unprogrammed '1' = Bit is set '0' = Bit is cleared

bit 7 **DEBUG:** Background Debugger Enable bit

1 = Background debugger disabled; RB6 and RB7 configured as general purpose I/O pins

0 = Background debugger enabled; RB6 and RB7 are dedicated to In-Circuit Debug

bit 6 XINST: Extended Instruction Set Enable bit

1 = Instruction set extension and Indexed Addressing mode enabled

0 = Instruction set extension and Indexed Addressing mode disabled (Legacy mode)

bit 5 STVREN: Stack Overflow/Underflow Reset Enable bit

1 = Reset on stack overflow/underflow enabled0 = Reset on stack overflow/underflow disabled

bit 4-1 **Unimplemented:** Read as '0'

bit 0 WDTEN: Watchdog Timer Enable bit

1 = WDT enabled

0 = WDT disabled (control is placed on the SWDTEN bit)

### REGISTER 23-2: CONFIG1H: CONFIGURATION REGISTER 1 HIGH (BYTE ADDRESS 300001h)

U-0	U-0	U-0	U-0	U-0	R/WO-1	U-0	U-0
(1)	(1)	(1)	(1)	(2)	CP0	_	_
bit 7							bit 0

Legend:

R = Readable bit WO = Write-Once bit U = Unimplemented bit, read as '0'

-n = Value when device is unprogrammed '1' = Bit is set '0' = Bit is cleared

bit 7-3 **Unimplemented:** Read as '0'

bit 2 **CP0:** Code Protection bit

1 = Program memory is not code-protected

0 = Program memory is code-protected

bit 1-0 Unimplemented: Read as '0'

**Note 1:** The value of these bits in program memory should always be '1'. This ensures that the location is executed as a NOP if it is accidentally executed.

2: This bit should always be maintained as '0'.

GOTO	Unconditional Branch					
Syntax:	GOTO k	GOTO k				
Operands:	$0 \le k \le 10$	48575				
Operation:	$k \rightarrow PC < 20:1 >$					
Status Affected:	None					
Encoding: 1st word (k<7:0>) 2nd word(k<19:8>)	1110 1111	1111 k <sub>19</sub> kkk	k <sub>7</sub> kkk kkkk	kkkk <sub>0</sub> kkkk <sub>8</sub>		
Description:	GOTO allows an unconditional branch anywhere within entire 2-Mbyte memory range. The 20-bit value 'k' is loaded into PC<20:1>. GOTO is always a two-cycle					

instruction.

Words: 2 Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>,	No operation	Read literal 'k'<19:8>, Write to PC
No operation	No operation	No operation	No operation

Example: GOTO THERE

After Instruction

PC = Address (THERE)

INCF	Increment	f				
Syntax:	INCF f {,c	l {,a}}				
Operands:	$0 \le f \le 255$ $d \in [0,1]$ $a \in [0,1]$					
Operation:	(f) + $1 \rightarrow de$	est				
Status Affected:	C, DC, N,	OV, Z				
Encoding:	0010	10da	ffff	ffff		
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'.					
	If 'a' is '0', the Access Bank is selected If 'a' is '1', the BSR is used to select the GPR bank.					
	If 'a' is '0' and the extended instruction set is enabled, this instruction operate in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode" for details.					
Words:	1					
Cycles:	1					
Q Cycle Activity:						
Q1	Q2	Q3		Q4		
Decode	Read register 'f'	Proces Data		Write to destination		

Example:	INCF		CNT,	1,	0
Before Instruct CNT Z C DC After Instructio	= = = =	FFh 0 ?			
CNT Z C DC	= = = =	00h 1 1 1			

SLE	ĒΡ	Enter Sleep Mode							
Synta	ax:	SLEEP	SLEEP						
Oper	ands:	None	None						
Oper	ation:								
Status Affected: TO, PD									
Enco	ding:	0000	0000 0000 0000 0011						
Desc	ription:	cleared. The	The Power-Down status bit $(\overline{PD})$ is cleared. The Time-out status bit $(\overline{TO})$ is set. The Watchdog Timer and its postscaler are cleared.						
		•	The processor is put into Sleep mode with the oscillator stopped.						
Word	ls:	1	1						
Cycle	es:	1							
Q C	ycle Activity:								
	Q1	Q2	Q3		Q4				
	Decode	No operation	Process	s	Go to Sleen				

<u>-xample:</u>		SLEEF
Before In	struc	ction
TO	=	?
PD	=	?
After Inst	ructio	on
TO	=	1 †
PD	=	0

† If WDT causes wake-up, this bit is cleared.

SUB	FWB	Sub	tract f fr	om W with Bo	rrow			
Synta	ax:	SUB	FWB f	{,d {,a}}				
•	ands:	$0 \le f \le 255$						
		$d \in [0,1]$ $a \in [0,1]$						
Oper	ation:	$(W) - (f) - (\overline{C}) \rightarrow dest$						
	s Affected:		V, C, DC	•				
Enco	dina:			01da fff	f ffff			
Encoding: Description:		Subtract register 'f' and Carry flag (borrow) from W (2's complement method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored in register 'f'.						
		ʻa' is	-	e Access Bank BSR is used to				
		set is Inde when Sect Bit-0	s enabled xed Liter never f ≤ tion 24.2 Oriented	d the extended d, this instruction al Offset Addre 95 (5Fh). See .3 "Byte-Orien Instructions t Mode" for de	on operates in essing mode inted and in Indexed			
Word	s:	1						
Cycle	es:	1						
Q C	ycle Activity:							
ı	Q1		Q2	Q3	Q4			
	Decode		ead	Process	Write to			
		regi	ster 'f'	Data	destination			
	<u>nple 1:</u>		UBFWB	REG, 1, 0				
	Before Instruc REG	tion =	3					
	W	=	2					
	C After Instructio	= nn	1					
	REG	=	FF					
	W	=	2					
	C Z		Λ					
_	_	=	0					
	N		0	esult is negativ	⁄e			
	N nple 2:	= = S1	0		/e			
	N n <u>ple 2:</u> Before Instruc	= = S1	0 1 ;r UBFWB		ve			
	N n <u>ple 2:</u> Before Instruc REG W	= = S1 tion = =	0 1 ;r UBFWB 2 5		ve			
	N nple 2: Before Instruc REG W C	= = S1 tion = = =	0 1 ;r UBFWB		/e			
	N n <u>ple 2:</u> Before Instruc REG W	= = S1 tion = = =	0 1 ;r UBFWB 2 5 1		⁄e			
	N nple 2: Before Instruc REG W C After Instructic REG W	= = Si tion = = = on =	0 1 ;r UBFWB 2 5 1 2 3		ve			
	N nple 2: Before Instruc REG W C After Instructic REG	= = Si tion = = = = on =	0 1 ; r UBFWB 2 5 1		/e			
	N nple 2: Before Instruc REG W C After Instructio REG W C Z	= = Si tion = = = on = =	0 1 ; r UBFWB 2 5 1 2 3 1 0					
Exam	N nple 2: Before Instruc REG W C After Instructio REG W C Z N	=	0 1 ; r UBFWB 2 5 1 2 3 1 0	REG, 0, 0				
Exam	N nple 2: Before Instruction REG W C After Instruction REG W C Z N nple 3: Before Instruc	= SI tion = = On = = = SI tion	0 ; r UBFWB 2 5 1 2 3 1 0 ; r UBFWB	REG, 0, 0				
Exam	N nple 2: Before Instruction REG W C After Instruction REG W C Z N nple 3: Before Instruct REG W C Z N	=	0 ; r ; r ; r ; r ; r ; r ; r ; r ; r ;	REG, 0, 0				
Exam	N nple 2: Before Instruction REG W C After Instruction REG W C Z N nple 3: Before Instruct REG W C C C C C C C C C C C C C C C C C C	=	0 1 ;r UBFWB 2 5 1 2 3 1 0 ;r UBFWB	REG, 0, 0				
Exam	N nple 2: Before Instruct REG W C After Instruction REG W C Z N nple 3: Before Instruct REG W C After Instruct	=	0 ; r UBFWB 2 5 1 2 3 1 0 0 ; r UBFWB 1 2 0	REG, 0, 0				
Exam	N nple 2: Before Instruction REG W C After Instruction REG W C Z N nple 3: Before Instruction REG W C C After Instruction REG W C C After Instruction REG W C C After Instruction REG W C REG W REG W	=	0 1 ;r UBFWB 2 5 1 2 3 1 0 ;r UBFWB 1 2 0 0 2	REG, 0, 0				
Exam	N nple 2: Before Instruction REG W C After Instruction REG W C Z N nple 3: Before Instruct REG W C After Instruction REG W C After Instruction REG	=	0 ; r UBFWB 2 5 1 2 3 1 0 ; r UBFWB 1 2 0 0 2 1	REG, 0, 0				

## 26.2 DC Characteristics: Power-Down and Supply Current PIC18F85J90 Family (Industrial) (Continued)

PIC18F85J90 Family (Industrial)		Standard Operating Conditions (unless otherwise stated)  Operating temperature -40°C ≤ TA ≤ +85°C for industrial							
Param No.	Device	Тур	Max	Units		Conditions			
	Supply Current (IDD) <sup>(2)</sup>								
	All devices	10.5	22	μA	-40°C	\/ 0.0\/			
		13.4	28	μA	+25°C	$V_{DD} = 2.0V,$ $V_{DDCORE} = 2.0V^{(4)}$			
		17.6	40	μA	+85°C	VDDCORE = 2.0V			
	All devices	13.2	30	μA	-40°C	\/pp = 0.5\/	Fosc = 32 kHz <sup>(3)</sup>		
		16.2	35	μΑ	+25°C	VDD = 2.5V, VDDCORE = 2.5V <sup>(4)</sup>	\\\DDCODE = 2.5\\(4\) \\\(SEC_F\)	(SEC_RUN mode,	
		20.7	50	μΑ	+85°C		Timer1 as clock)		
	All devices	39	120	μΑ	-40°C				
		58	150	μΑ	+25°C	VDD = 3.3V <sup>(5)</sup>			
		75	190	μΑ	+85°C				
	All devices	5.7	15	μΑ	-40°C	V <sub>DD</sub> = 2.0V,			
		8.9	20	μΑ	+25°C	VDD = 2.0V, $VDDCORE = 2.0V^{(4)}$			
		12.8	26	μΑ	+85°C				
	All devices	6.6	17	μΑ	-40°C	\/DD = 2.5\/	Fosc = 32 kHz <sup>(3)</sup>		
		9.7	24	μA	+25°C	$V_{DD} = 2.5V,$ $V_{DDCORE} = 2.5V^{(4)}$	(SEC_IDLE mode,		
		13.7	30	μA	+85°C	15566.KE <b>2.0</b> 1	Timer1 as clock)		
	All devices	39	115	μA	-40°C				
		52.8	145	μA	+25°C	VDD = 3.3V <sup>(5)</sup>			
		72.7	185	μΑ	+85°C				

- Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in a high-impedance state and tied to VDD or Vss, and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).
  - 2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;

MCLR = VDD; WDT enabled/disabled as specified.

- 3: Standard, low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.
- 4: Voltage regulator is disabled (ENVREG tied to Vss).
- 5: Voltage regulator is enabled (ENVREG tied to VDD).
- 6: Resistor ladder current is not included.
- 7: Connecting an actual display will increase the current consumption depending on the size of the LCD.

### TABLE 26-8: PLL CLOCK TIMING SPECIFICATIONS (VDD = 2.15V TO 3.6V)

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
F10	Fosc	Oscillator Frequency Range	4	_	10	MHz	HS mode only
F11	Fsys	On-Chip VCO System Frequency	16	_	40	MHz	HS mode only
F12	t <sub>rc</sub>	PLL Start-up Time (Lock Time)	_	_	2	ms	
F13	$\Delta$ CLK	CLKO Stability (Jitter)	-2	_	+2	%	

<sup>†</sup> Data in "Typ" column is at 3.3V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

### TABLE 26-9: INTERNAL RC ACCURACY (INTOSC AND INTRC SOURCES)

PIC18F85J90 Family (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for industrial						
Param No.	Device	Min	Тур	Max	Units	Conditions		
	INTOSC Accuracy @ Freq = 8 MHz, 4 MHz, 2 MHz, 1 MHz, 500 kHz, 250 kHz, 125 kHz, 31						Hz, 31 kHz <sup>(1)</sup>	
	All Devices	-2	±1	2	%	+25°C	VDD = 2.7-3.3V	
		-5	_	5	%	-10°C to +85°C	VDD = 2.0-3.3V	
		-10	±1	10	%	-40°C to +85°C	VDD = 2.0-3.3V	
	INTRC Accuracy @ Freq = 31 kHz <sup>(1)</sup>							
	All Devices	26.562	_	35.938	kHz	-40°C to +85°C	VDD = 2.0-3.3V	

Note 1: The accuracy specification of the 31 kHz clock is determined by which source is providing it at a given time. When INTSRC (OSCTUNE<7>) is '1', use the INTOSC accuracy specification. When INTSRC is '0', use the INTRC accuracy specification.

#### **INDEX** Α Baud Rate Error, Calculating ...... 260 Baud Rates, Asynchronous Modes ...... 261 A/D ......271 High Baud Rate Select (BRGH Bit) .......260 A/D Converter Interrupt, Configuring ......275 Operation in Power-Managed Modes ...... 260 Acquisition Requirements .......276 ADCAL Bit ......279 ADCON0 Register ......271 Associated Registers, Receive ............................... 268 ADCON1 Register ......271 ADCON2 Register ......271 ADRESL Register ......271 Analog Port Pins, Configuring ......277 Associated Registers, Receive ............................... 270 Associated Registers .......279 Automatic Acquisition Time ......277 Calibration .......279 Configuring the Module ......275 Auto-Wake-up on Sync Break Character ...... 249 Conversion Clock (TAD) ......277 Conversion Requirements ......392 В Operation in Power-Managed Modes ......279 Special Event Trigger (CCP) ......278 Use of the CCP2 Trigger ......278 Bias Generation (LCD) Absolute Maximum Ratings .......359 **Block Diagrams** Load Conditions for Device Timing A/D ......274 Analog Input Model ...... 275 Parameter Symbology .......374 Temperature and Voltage Specifications .......375 ACKSTAT ......225 Capture Mode Operation ...... 156 ACKSTAT Status Flag ......225 Comparator Analog Input Model .......285 ADCON1 Register ......271 Comparator Voltage Reference Output ADCON2 Register ......271 ADDLW ......311 Connections for On-Chip Voltage Regulator .......... 299 Addressable Universal Synchronous Asynchronous Receiver Transmitter (AUSART). See AUSART. EUSART Receive .......247 EUSART Transmit ......245 ADDWF ......311 External Power-on Reset Circuit (Slow VDD Power-up) .......53 ADRESH Register ......271 Fail-Safe Clock Monitor ...... 301 ADRESL Register ......271, 274 Generic I/O Port Operation ...... 115 Analog-to-Digital Converter. See A/D. ANDLW ......312 ANDWF .......313 LCD Driver Module ......163 Assembler LCD Regulator Connections (M0 and M1) ...... 170 MPASM Assembler ......356 **AUSART** Asynchronous Mode .......262 MSSP (SPI Mode) ......191 Associated Registers, Receive ......265 On-Chip Reset Circuit ......51 Associated Registers, Transmit .......263 PIC18F6XJ90 ...... 12 PIC18F8XJ90 ......13 Setting up 9-Bit Mode with Address Detect ..... 264 PWM Operation (Simplified) ...... 159

Flash Program Memory	87	Serial Clock (SCK/SCL)	207
Associated Registers	95	Slave Mode	
Control Registers	88	Addressing	205
EECON1 and EECON2		Addressing Masking	206
TABLAT (Table Latch) Register	90	Reception	207
TBLPTR (Table Pointer) Register	90	Transmission	
Erase Sequence		Sleep Operation	229
Erasing	92	Stop Condition Timing	228
Operation During Code-Protect		INCF	
Reading		INCFSZ	
Table Pointer		In-Circuit Debugger	303
Boundaries Based on Operation	90	In-Circuit Serial Programming (ICSP)	
Table Pointer Boundaries		Indexed Literal Offset Addressing	== ., == .
Table Reads and Table Writes		and Standard PIC18 Instructions	352
Write Sequence		Indexed Literal Offset Mode	
Writing		Indirect Addressing	
Unexpected Termination		INFSNZ	
Write Verify		Initialization Conditions for all Registers	
FSCM. See Fail-Safe Clock Monitor.	90	Instruction Cycle	
rocivi. See raii-Sale Clock Moriitor.		Clocking Scheme	
G			
GOTO	226	Flow/Pipelining	
GO10	320	Instruction Set	
H		ADDLW	
Hardwara Multiplior	07	ADDWF	
Hardware Multiplier		ADDWF (Indexed Literal Offset Mode)	
		ADDWFC	
Operation		ANDLW	
Performance Comparison	97	ANDWF	
I		BC	313
	445	BCF	314
I/O Ports		BN	314
Input Voltage Considerations		BNC	315
Open-Drain Outputs		BNN	315
Output Pin Drive		BNOV	316
Pin Capabilities		BNZ	316
Pull-up Configuration		BOV	319
I <sup>2</sup> C Mode (MSSP)		BRA	317
Acknowledge Sequence Timing		BSF	317
Associated Registers	234	BSF (Indexed Literal Offset Mode)	353
Baud Rate Generator	221	BTFSC	
Bus Collision		BTFSS	318
During a Repeated Start Condition	232	BTG	
During a Stop Condition	233	BZ	
Clock Arbitration	222	CALL	
Clock Stretching	214	CLRF	
10-Bit Slave Receive Mode (SEN = 1)	214	CLRWDT	
10-Bit Slave Transmit Mode		COMF	
7-Bit Slave Receive Mode (SEN = 1)		CPFSEQ	
7-Bit Slave Transmit Mode		CPFSGT	
Clock Synchronization and the CKP Bit			
Effects of a Reset		CPFSLT	
General Call Address Support		DAW	
I <sup>2</sup> C Clock Rate w/BRG		DCFSNZ	
Master Mode		DECF	
Baud Rate Generator		DECFSZ	
		Extended Instructions	
Operation		Considerations when Enabling	
Reception		Syntax	
Repeated Start Condition Timing		Use with MPLAB IDE Tools	
Start Condition Timing		General Format	307
Transmission	225	GOTO	
Multi-Master Communication, Bus Collision		INCF	326
and Arbitration		INCFSZ	
Multi-Master Mode		INFSNZ	
Opera <u>tion</u>		IORLW	
Read/Write Bit Information (R/W Bit)	. 205, 207	IORWF	
Registers	200	1011111	

LFSR329
MOVF329
MOVFF
MOVLB
MOVLW
MOVWF
MULLW332
MULWF332
NEGF
NOP333
Opcode Field Descriptions
·
POP
PUSH334
RCALL335
RESET335
RETFIE
RETLW
RETURN
RLCF337
RLNCF338
RRCF
RRNCF
SETF
SETF (Indexed Literal Offset Mode)353
SLEEP340
Standard Instructions305
SUBFWB340
SUBLW341
SUBWF
SUBWFB
SWAPF342
TBLRD343
TBLWT344
TSTFSZ
XORLW
XORWF
INTCON Register
RBIF Bit118
INTCON Registers101
Inter-Integrated Circuit. See I <sup>2</sup> C Mode.
Internal Oscillator Block41
Adjustment41
INTOSC Frequency Drift41
INTOSC Output Frequency41
OSC1, OSC2 Pin Configuration41
Internal RC Oscillator
Use with WDT
Internal Voltage Regulator Specifications
Internet Address413
Interrupt Sources
A/D Conversion Complete275
Capture Complete (CCP)156
Compare Complete (CCP)
Interrupt-on-Change (RB7:RB4)
TMR0 Overflow
TMR1 Overflow141
TMR2 to PR2 Match (PWM)159
TMR3 Overflow149, 151
Interrupts
•
During, Context Saving114
INTx Pin
PORTB, Interrupt-on-Change114
TMR0114
Interrupts, Flag Bits
Interrupt-on-Change (RB7:RB4) Flag (RBIF Bit) 118

INTOSC, INTRC. See Internal Oscillator Block.	200
IORLW	
IORWF	
IPR Registers	110
L	
LCD	
	100
Associated Registers	
Bias Generation	
Bias Configurations	
M0 and M1	
M2	
M3	
Bias Types	
LCD Voltage Regulator	
Charge Pump170,	173
Clock Source Selection	168
Configuring the Module	188
Frame Frequency	
Interrupts	
LCDCON Register	
LCDDATA Registers	
LCDPS Register	
LCDREG Register	
LCDSE Registers	
Multiplex Types	
Operation During Sleep	
Pixel Control	
Segment Enables	
Waveform Generation	174
LCD Driver	
LCDCON Register	
LCDDATA Registers	164
LCDPS Register	164
LCDREG Register	164
LCDSE Registers	164
LFSR	329
Liquid Crystal Display (LCD) Driver	
Low-Voltage Detection	
101.0g0	
M	
Master Clear (MCLR)	53
Master Synchronous Serial Port (MSSP). See MSSP.	. 00
Memory Organization	63
Data Memory	
Program Memory	
Memory Programming Requirements	
Microchip Internet Web Site	
MOVF	
MOVFF	
MOVLB	330
MOVLW	331
MOVSF	349
MOVSS	350
MOVWF	331
MPLAB ASM30 Assembler, Linker, Librarian	356
MPLAB Integrated Development	
Environment Software	355
MPLAB PM3 Device Programmer	
MPLAB REAL ICE In-Circuit Emulator System	
MPLINK Object Linker/MPLIB Object Librarian	
osjott osjott Elstandir	200